



Click [here](#) for the 3D model.

**General Information**

Series	SMD Comm COG HV
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	false
AEC-Q200	No
Typical Component Weight	310 mg
Shelf Life	78 Weeks
MSL	1

**Specifications**

Capacitance	3000 pF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	5%
Voltage DC	2000 VDC
Dielectric Withstanding Voltage	2400 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

**Dimensions**

Chip Size	1825
L	4.5mm +/-0.3mm
W	6.4mm +/-0.4mm
T	2.5mm +/-0.20mm
S	2.3mm MIN
B	0.6mm +/-0.35mm

**Packaging Specifications**

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	500

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.